

# INDUSTRY INTELLIGENCE

In 2024, IPC solidified its position as a global thought leader by delivering actionable insights shaping the future of electronics manufacturing. Partnering with top industry leaders, IPC produced reports on workforce development, semiconductor advanced packaging, sustainability, AI, manufacturing policy, and design. These reports provided valuable guidance to electronics manufacturers and informed strategic investments.

IPC's work also served as a tool for educating governments on challenges in the electronics industry. In Europe, IPC collaborated with Decision Etudes y Conseil and in4ma to publish [Securing the European Union's Electronics Ecosystem](#). This report, supported by 80+ companies and associations, gained attention at the highest levels of the EU and across European capitals. In North America, IPC released [AI-Based Data Centers for the United States](#), building on research for the U.S. Government. These reports help governments address industrial vulnerabilities and embrace innovation.

IPC strengthened its statistical programs, increasing EMS and PCB data participation in North America and deepening its partnership with in4ma on European EMS data. Additionally, IPC continued publishing monthly economic and [global sentiment reports](#).

The launch of Industry Intelligence Insights, IPC's new industry intelligence newsletter, offers monthly updates and recommendations to become a vital resource to the growing readership.

- > **[Outlook for Data Analytics in the Electronics Manufacturing Industry](#)**: Highlighted the transformative role of data analytics, focusing on real-time analysis and workforce upskilling.
- > **[Building Electronics Better](#)**: Addressed workforce shortages with scalable solutions and structured career pathways.
- > **[Securing the European Union's Electronics Ecosystem](#)**: Advocated for strategic investments in PCBs and assembly to support Europe's digital and green transitions.
- > **[Better Electronics by Design](#)**: Explored Design for Excellence (DfX) strategies for interoperability in electronics systems.
- > **[Advanced Packaging to Board-Level Integration](#)**: Tackled challenges in advanced packaging for 5G and aerospace applications.
- > **[AI-Based Data Centers for the United States](#)**: Provided strategies to enhance U.S. competitiveness in AI-driven manufacturing.
- > **[Why Double Materiality Assessments Matter](#)**: Offered guidance for navigating the EU's CSRD and leveraging double materiality assessments for sustainability.
- > **[New Communication Channels](#)**: Launched [Industry Intelligence Insights](#), a newsletter with exceptional engagement, delivering monthly updates to industry professionals.
- > **[External Engagement](#)**: Produced synopses and blogs of major reports, ensuring accessibility for non-industry stakeholders and amplifying their impact with policymakers and media.

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